

CRYSTAL OSCILLATOR SPXO

SG-310 series

- Frequency range : 2 MHz to 80 MHz
- Supply voltage : 1.8 V Typ. / 2.5 V Typ. / 3.3 V Typ.
- Current consumption : 1.5 mA Typ.
(SEF: 1.8 V No load condition 48 MHz)
- Function : Standby(\overline{ST})
- External dimensions : 3.2 × 2.5 × 1.05 mm



Product Number (please contact us)
Q33310xx0xxx00



Actual size

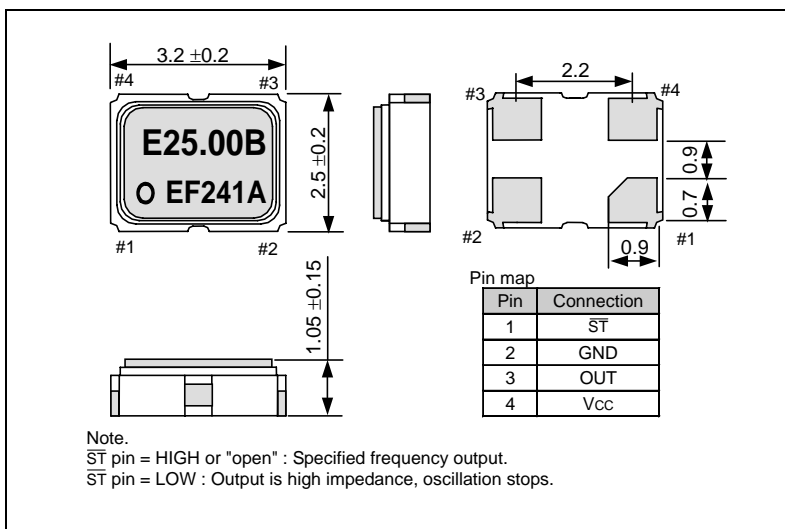


Specifications (characteristics)

Item	Symbol	Specifications					Remarks
		SG-310 SEF	SG-310 SDF	SG-310 SCF	SG-310 SDN	SG-310 SCN	
Output frequency range	f_o	2.000 MHz to 48.000 MHz			3.000 MHz to 80.000 MHz		
Supply voltage	V_{CC}	1.8 V Typ. 1.6 V to 2.2 V	2.5 V Typ. 2.2 V to 3.0 V	3.3 V Typ. 2.7 V to 3.6 V	2.5 V Typ. 2.2 V to 2.7 V	3.3 V Typ. 2.7 V to 3.6 V	
Temperature range	Storage temperature	-40 °C to +125 °C					Store as bare product after unpacking
	Operating temperature	-40 °C to +85 °C					
Frequency tolerance	f_{tol}	B: $\pm 50 \times 10^{-6}$, C: $\pm 100 \times 10^{-6}$ L: $\pm 50 \times 10^{-6}$, M: $\pm 100 \times 10^{-6}$					-20 °C to +70 °C
		-			D: $\pm 20 \times 10^{-6}$, S: $\pm 25 \times 10^{-6}$		-40 °C to +85 °C
		-			R: $\pm 25 \times 10^{-6}$		-20 °C to +70 °C
		-			P: $\pm 20 \times 10^{-6}$		-30 °C to +85 °C
		-			J: $\pm 25 \times 10^{-6}$		-40 °C to +85 °C
Current consumption	I_{CC}	1.5 mA Max.	1.5 mA Max.	1.5 mA Max.	4.0 mA Max.	5.0 mA Max.	No load condition, 2 MHz $\leq f_o \leq$ 4 MHz
		1.5 mA Max.	1.5 mA Max.	2.0 mA Max.			No load condition, 4 MHz $\leq f_o \leq$ 8 MHz
		1.5 mA Max.	2.0 mA Max.	2.5 mA Max.			No load condition, 8 MHz $\leq f_o \leq$ 16 MHz
		2.0 mA Max.	2.0 mA Max.	2.5 mA Max.			No load condition, 16 MHz $\leq f_o \leq$ 25 MHz
		2.0 mA Max.	2.5 mA Max.	3.5 mA Max.			No load condition, 25 MHz $\leq f_o \leq$ 33 MHz
		3.0 mA Max.	3.5 mA Max.	4.5 mA Max.			No load condition, 33 MHz $\leq f_o \leq$ 48 MHz
Stand-by current	I_{std}	0.7 μ A Max. (0.2 μ A Typ.)	1.5 μ A Max. (0.5 μ A Typ.)	2.0 μ A Max. (1.0 μ A Typ.)	6.0 mA Max. 7.0 mA Max.		No load condition, 48 MHz $\leq f_o \leq$ 80 MHz
Symmetry	SYM	45 % to 55 %	45 % to 55 %	45 % to 55 %	45 % to 55 %	50 % V_{CC} level $L_{CMOS} \leq 15$ pF	
		40 % to 60 %					40 % to 60 %
High output voltage	V_{OH}	90 % V_{CC} Min.					$I_{OH} = -3$ mA
Low output voltage	V_{OL}	10 % V_{CC} Max.					$I_{OL} = 3$ mA
Output load condition (CMOS)	L_{CMOS}	15 pF Max.					
Output enable / disable input voltage	V_{IH}	80 % V_{CC} Min.			70 % V_{CC} Min.		\overline{ST} terminal
	V_{IL}	20 % V_{CC} Max.			30 % V_{CC} Max.		
Rise time / Fall time	t_r / t_f	4 ns Max.					20 % V_{CC} to 80 % V_{CC} level, $L_{CMOS} = 15$ pF
Start-up time	t_{str}	10 ms Max.			2 ms Max.		$t=0$ at 90 % V_{CC}
Frequency aging	f_{aging}	$\pm 5 \times 10^{-6}$ / year Max.			$\pm 3 \times 10^{-6}$ / year Max.		+25 °C, First year, $V_{CC} = 1.8$ V, 2.5 V, 3.3 V
		-			$\pm 10 \times 10^{-6}$ Max.		+25 °C, 10 years

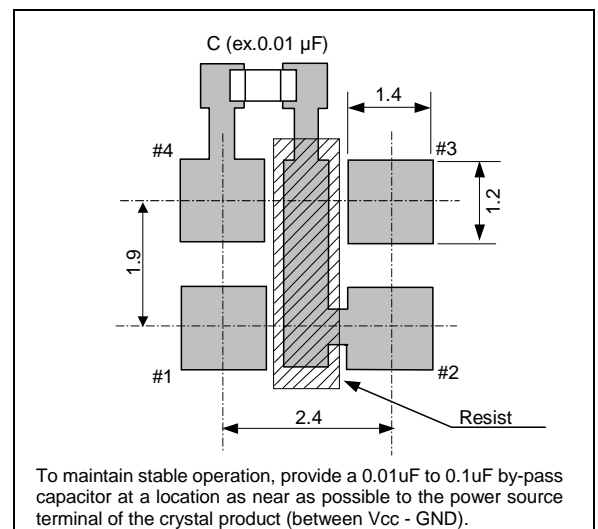
External dimensions

(Unit:mm)



Footprint (Recommended)

(Unit:mm)



“QMEMS” EPSON TOYOCOM

In order to meet customer needs in a rapidly advancing digital, broadband and ubiquitous society, we are committed to offering products that are one step ahead of the market and a rank above the rest in quality. To achieve our goals, we follow a “3D (three device) strategy” designed to drive both horizontal and vertical growth. We will to grow our three device categories of “Timing Devices”, “Sensing Devices” and “Optical Devices”, and expand vertical growth through a combination of products from these categories.

A Quartz MEMS is any high added value quartz device that exploits the characteristics of quartz crystal material but that is produced using MEMS (micro-electro-mechanical system) processing technology.

Market needs are advancing faster than previously imagined toward smaller, more stable crystal products, but we will stay ahead of the curve by rolling out products that exceed market speed and quality requirements. We want to further accelerate the 3D strategy by QMEMS.

Quartz devices have become crucial in the network environment where products are increasingly intended for broadband, ubiquitous applications

and where various types of terminals can transfer information almost immediately via LAN and WAN on a global scale. Epson Toyocom Corporation addresses every single aspect within a network environment. The new corporation offers “Digital Convergence” solutions to problems arising with products for consumer use, such as, core network systems and automotive systems.



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PROMOTION OF ENVIRONMENTAL MANAGEMENT SYSTEM CONFORMING TO INTERNATIONAL STANDARDS

At Epson Toyocom, all environmental initiatives operate under the Plan-Do-Check-Action(PDCA) cycle designed to achieve continuous improvements. The environmental management system (EMS) operates under the ISO 14001 environmental management standard.

All of our major manufacturing and non-manufacturing sites, in Japan and overseas, completed the acquisition of ISO 14001 certification.

ISO 14000 is an international standard for environmental management that was established by the International Standards Organization in 1996 against the background of growing concern regarding global warming, destruction of the ozone layer, and global deforestation.




WORKING FOR HIGH QUALITY

In order provide high quality and reliable products and services than meet customer needs,

Epson Toyocom made early efforts towards obtaining ISO9000 series certification and has acquired ISO9001 for all business establishments in Japan and abroad. We have also acquired ISO/TS 16949 certification that is requested strongly by major automotive manufacturers as standard.

ISO/TS16949 is the international standard that added the sector-specific supplemental requirements for automotive industry based on ISO9001.

► Explanation of the mark that are using it for the catalog

	► Pb free.
	► Complies with EU RoHS directive. *About the products without the Pb-free mark. Contains Pb in products exempted by EU RoHS directive. (Contains Pb in sealing glass, high melting temperature type solder or other.)
	► The products have been designed for high reliability applications such as Automotive.

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